

Title (en)
PROCESS FOR METALLIZING AN INSULATING SURFACE

Publication
EP 0204906 A3 19920115 (DE)

Application
EP 86104143 A 19860325

Priority
DE 3512342 A 19850404

Abstract (en)
[origin: EP0204906A2] The adhesive strength of, in particular, ductile metal layers bound predominantly by mechanical anchorage to the substrate is enhanced by a controlled increase of the hardness of these metal layers by formation of an alloy or by precipitation hardening, preferably in the zone of the metal layers close to the substrate. This is achieved by means of an interlayer which is applied to the substrates before the application of the metal layer or is effected afterwards by a heat treatment.

IPC 1-7
C23C 18/18

IPC 8 full level
C04B 41/90 (2006.01); **C23C 18/18** (2006.01); **C23C 28/02** (2006.01)

CPC (source: EP)
C23C 18/1855 (2013.01); **C23C 18/1889** (2013.01)

Citation (search report)

- [X] DE 2314236 A1 19731018 - PHILIPS NV
- [X] DE 2142169 A1 19730301 - TECHNOGRAPH INTERNATIONAL DEVE
- [X] DE 2004133 A1 19710812 - LICENTIA GMBH

Designated contracting state (EPC)
AT BE CH DE FR GB IT LI LU NL SE

DOCDB simple family (publication)
DE 3512342 A1 19861009; DE 3512342 C2 19931223; EP 0204906 A2 19861217; EP 0204906 A3 19920115; JP S61231179 A 19861015

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DE 3512342 A 19850404; EP 86104143 A 19860325; JP 7440186 A 19860402